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- 6.

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1.

(composite)  
 (bulk)  
 (hardness)  
 (toughness) 가

(1) / (chemical or  
 physical vapor deposition), (electrodeposition), (thermal  
 spraying) overlay coating, (2)  
 (diffusion coating) (chemical conversion  
 coating), (3)  
 (ion implantation)

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가 . overlay coating 가 가

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가 , , , -

(alloy/composite metal coating) 가 ,

가 가 (organic coating)

(inorganic coating) , ,

가 / / 가 .

2.

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(1989 ), 600

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3.

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Campbell / 1  
Schiller 1  
Table 2  
Table 3

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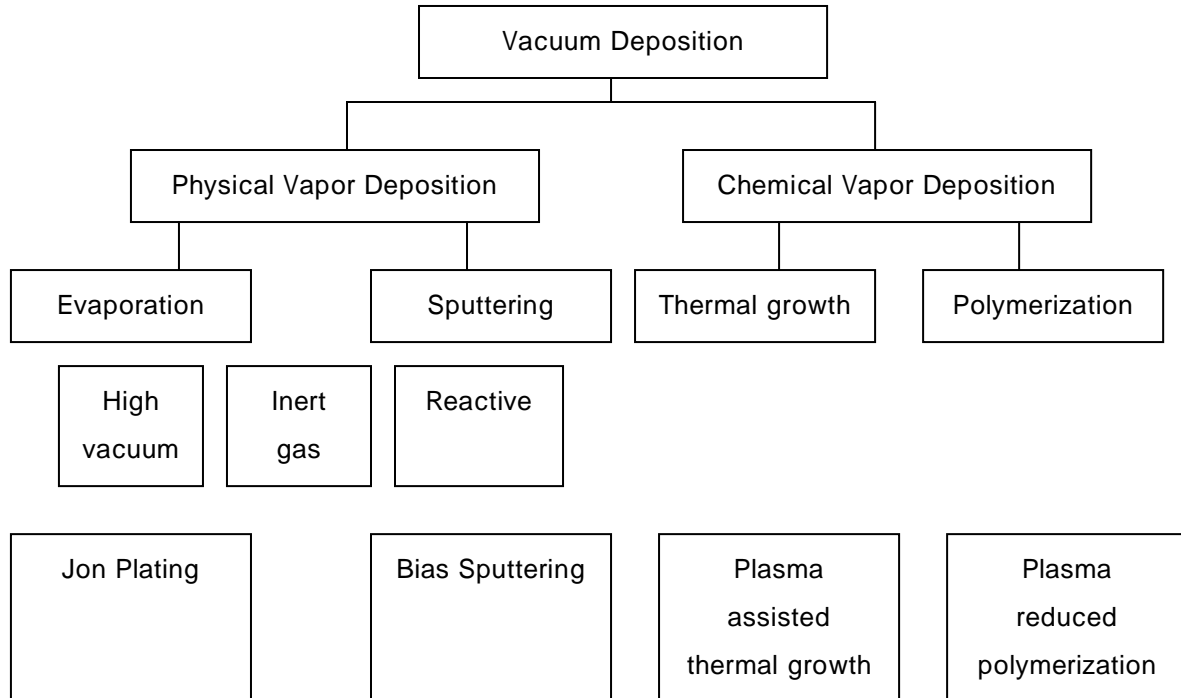
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raw material for surface coating, thermal spray coating, electrodeposition coating, physical vapor deposition coating, chemical vapor deposition coating, polymer coating, weld surface coating, characterization of surface coating, industrial applications of functional coating

Figure 1. Survey of vacuum deposition techniques



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**Table 1. Chemical Methods of Film Preparation**

Basic Class		Method
Thin Film	Formation from the medium	Electroplating Ion Plating Chemical Reduction Vapor Phase Reduction Plasma Reduction
	Formation from substrate	Gaseous Anodization Thermal Reduction Plasma Reduction
Thick Film		Glazing Electrophoresis Flame Spraying Painting

**Table 2. Methods of Fabricating Coatings**

Atomic Deposition	Surface Modification
Electrolytic Environment <ul style="list-style-type: none"> <li>- Electroplating</li> <li>- Electroless Plating</li> <li>- Fused Salt Electrolysis</li> <li>- Chemical Displacement</li> </ul> Vacuum Environment <ul style="list-style-type: none"> <li>- Vacuum Evaporation</li> <li>- Ion Beam Deposition</li> <li>- Molecular Beam Epitaxy</li> </ul> Plasma Environment <ul style="list-style-type: none"> <li>- Sputter Deposition</li> <li>- Activated Reactive Evaporation</li> <li>- Plasma Polymerization</li> <li>- Ion Plating</li> </ul> Chemical Vapor Environment <ul style="list-style-type: none"> <li>- Chemical Vapor Deposition               <ul style="list-style-type: none"> <li>: Reduction</li> <li>Decomposition</li> <li>Plasma Enhanced</li> </ul> </li> <li>- Spray Pyrolysis</li> </ul> Liquid Phase Epitaxy	Chemical Conversion <ul style="list-style-type: none"> <li>- Electric Oxidization</li> <li>- Fused Salts</li> </ul> Chemical-Liquid Chemical-Vapor <ul style="list-style-type: none"> <li>- Thermal</li> <li>- Plasma</li> </ul> Leaching Mechanical <ul style="list-style-type: none"> <li>- Spot Peening</li> </ul> Thermal Surface Enrichment <ul style="list-style-type: none"> <li>- Diffusion from Bulk</li> </ul> Sputtering Ion Implanation
Bulk Coatings	Particulate Deposition
Wetting Processes <ul style="list-style-type: none"> <li>- Painting</li> <li>- Dip Coating</li> </ul> Electrostatic Spraying <ul style="list-style-type: none"> <li>- Printing</li> <li>- Spin Coating</li> </ul> Cladding <ul style="list-style-type: none"> <li>- Explosive</li> <li>- Roll Bonding</li> </ul> Overlaying <ul style="list-style-type: none"> <li>- Weld Coating</li> </ul>	Thermal Spraying <ul style="list-style-type: none"> <li>- Plasma Spraying</li> <li>- D-Gun</li> <li>- Flame Spraying</li> </ul> Fusion Coatings <ul style="list-style-type: none"> <li>- Thick Film Ink</li> <li>- Enameling</li> <li>- Electrophoretic</li> </ul> Impact Plating

Table 3. Comparison of Surface Coating Processes and Deposits

	Vapor deposition	Electro - deposition	Thermal Spraying
Thickness/mm	0.001 - 0.2	0.02 - 0.5	0.1 - 1
Component geometry	Versatile	Versatile	Access to internal surface
Component size	Limited by chamber size	Limited by plating bath	No limit
Substrate material	Almost limitless	Almost limitless	Almost limitless
Substrate temperature/C	30 - 1000	100	200
Pretreatment	PVD – ion bombardment CVD – various	Chemical cleaning and etching	Clean and roughen surface
Post - treatment	Non/stress relief	Non/stress relief	Non
Coating porosity/%	Nil to small	Nil to small	1 - 15
Bond strength/MPa	High	100	20 - 140
Bond mechanism	Atomic, surface force	surface force	Mechanical
Control of coating thickness	Good	Good	Fairly good
Distortion of substrate	Low	Low	Low

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**Table 3. Comparison of Surface Coating Processes and Deposits (continued)**

	<b>Spray fusion</b>	<b>Welding</b>
<b>Thickness/mm</b>	0.5 - 1.5	1 - 20 or more
<b>Component geometry</b>	Controlled by size of torch or gun	
<b>Substrate material</b>	Metals or alloys of higher melting point than coating	
<b>Substrate temperature</b>	1050	1400
<b>Pretreatment</b>	Clean and roughen surface	Mechanical cleaning
<b>Post-treatment</b>	Substrate annealing/stress relief as required	
<b>Coating porosity/%</b>	Nil	Nil
<b>Bond strength/MPa</b>	High	High
<b>Bond mechanism</b>	Metallurgical	Metallurgical
<b>Control of coating thickness</b>	Moderate	Moderate-variable Mechanized - good
<b>Distortion of substrate</b>	Moderated	Can be high, depending on substrate geometry